

Nov. 9, 2022 (Wed.)

| | Monterosso (B1F) | Forum 1 (3F) | Forum 2 (3F) | Forum 3 (3F) | Vernaza (3F) |
|---------------|---|--|---|---|---|
| | Novel Package Substrate 1 | 2.5D and 3D Interconnect 1 | Package Materials and Process | Automotive and Power Electronics 1 | Special Session 1 |
| Session Chair | Dr. Jiho Joo | Prof. Bongyoung Yoo | Dr. Tae-Ik Lee | Prof. Jeong-Won Yoon | |
| 13:00 ~ 13:25 | O1-1 Dr. Gwang-Mun Choi, Dr. Jiho Joo, Ki-Seok Jang, Jin-Hyuk Oh, Chanmi Lee, Dr. Ho-Gyeong Yun, Dr. Seok Hwan Moon, In-Seok Kye, Yoon-Hwan Moon, Dr. Kwang-Seong Choi, Dr. Yong-Sung Eom / Electronics and Telecommunications Research Institutes (ETRI), Korea "Selectively-Aligned Anisotropic Solder Film for Fine-Pitch Interconnections" | (Invited) I1-1 Prof. Sanghwa Yoon / Hanyang University, Korea "CMP-less Metal Planarization for 3D Interconnection" | O1-2 Dr. Sunin Kang / Korea Institute of Machinery and Materials (KIMM), Korea Prof. Taek-Soo Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea "Mechanical Debonding of Thin Films for Advanced Electronic Applications" | O1-3 Na-Rae Kim, Kwang-Hun Jeong, Prof. Jun-Hong Park / Hanyang University, Korea "Measurement of Dynamic Properties of Multi-layered Semiconductors by Vibration Tests" | 13:00 ~ 15:00, Ultrafine Pitch PCB Manufacturing and Interconnect Process Tech University of Korea Korea Institute of Industrial Technology(KITECH) Korea Electronics Technology Institute(KETI) (Close Session) |
| 13:25 ~ 13:50 | O1-4 Dr. Wonyoung Choi, Dr. David Bokwoo Han / Genesem Inc., Korea Prof. Keejun Han / Hansung University, Korea "A Novel Selective EMI Shielding Process by Exploiting Tape Attach and Detach Sub-processes" | (Invited) I1-2 Prof. Hyo-Jong Lee / Dong-A University, Korea "Calculation of Copper Filling and Microstructural Analysis in TSV and PCB Patterns" | O1-5 Doheon Kim, Gahui Kim, Prof. Young-Cheon Kim, Prof. Young-Bae Park / Andong National University, Korea "Curing Condition Effects on the Interfacial Characteristics of Photosensitive Polyimide Capping Layer/ Cu RDL Structure" | (Invited) I1-3 Dr. Dongjin Kim / Korea Institute of Industrial Technology (KITECH), Korea "Heat-resistant Packaging Technologies of Wide Band-gap Power Modules" | |
| 13:50 ~ 14:15 | (Invited) I1-4 Eita Horiki / Sekisui Korea Co., Ltd., Korea "Build-up Dielectric Material that enables High Temp. Low Loss, High Toughness, High Yield Advanced FC-BGA Substrates" | (Invited) I1-5 Prof. Myung Jun Kim / Kyung Hee University, Korea "Additives in Cu Electrodeposition for TSV Filling" | (Invited) I1-6 Mitsuo Sugino / Senju Metal Industry Co., Ltd., Japan "Latest Soldering Material Technology for Semiconductor Assembly" | (Invited) I1-7 Dr. Hanbyul Kang / Korea Automotive Technology Institute (KATECH), Korea (On-line Presentation) "Reliability Challenges of Micro-electronics Packaging for Eco-friendly Car" | |
| 14:15 ~ 14:40 | (Invited) I1-8 Kosuke Tsukamoto / Shinko Electric Industries Co., Ltd., Japan "Demonstration of 2.3D Organic Package with Increased Interposer Size and Layer Count" | (Invited) I1-9 Yong-Tae Kwon / Nepes Corp., Korea "Die-stackable 3D Package Using Fan-out Technology" | (Invited) I1-10 Hatakeyama Keiichi / Showa Denko Materials Co., Ltd., Japan "Total Solution Activity of Showa Denko Materials for Future Advanced Semiconductor Packages" | (Invited) I1-11 Dr. Semin Park / Hyundai Mobis Co., Ltd., Korea "Power Semiconductor Module for Electrified Vehicles" | |
| 14:40 ~ 15:00 | Coffee Break | | | | |
| Session Chair | Prof. Sungdong Kim | | | | |
| 15:00 ~ 15:30 | Keynote Talk 1 - Prof. Sung Kyu Lim / Georgia Institute of Technology, USA (On-line Presentation) "TSV & Heterogeneous Integration" (Monterosso (B1F)) | | | | |
| 15:30 ~ 16:00 | Keynote Talk 2 - Jing (Jim) Cao / Universal Scientific Industrial Co., Ltd., ASE Group, China (On-line Presentation) "SiP, The Next Revolution for Microelectronics Packaging and The Challenges" (Monterosso (B1F)) | | | | |
| 16:00 ~ 16:20 | Coffee Break | | | | |

| | Monterosso (B1F) | Forum 1 (3F) | Forum 2 (3F) | Forum 3 (3F) | Vernaza (3F) |
|---------------|---|---|--|--|--------------|
| | Novel Package Substrate 2 | Emerging Technologies 1 | Flexible and Printed Electronics 1 | Automotive and Power Electronics 2 | |
| Session Chair | Prof. Hyo-Jong Lee | Dr. Kwang-Seong Choi | Dr. Sung-Wook Mhin | Dr. Dongjin Kim | |
| 16:20 ~ 16:45 | (Invited) I1-12 Hidetoshi Seki / Sumitomo Bakelite Co., Ltd., Japan "Next-Generation Packaging Solutions for High-speed Communications" | O1-6 Sung Min Jeon, Sang Yeob Kim, Sung Young Lee, Hyun-Jun Park, Byung-Geun Song, Mong-Hyun Cho, Dr. Jeong Tak Moon / MK Electron Co., Ltd., Korea "High Reliability of Bonded Au Coated Ag Bonding Wire in Gas-free Condition" | (Invited) I1-13 Prof. Yoonseok Park / Kyung Hee University, Korea (On-line Presentation) "Wireless, Skin-interfaced Pressure Sensors for Biomedical Application" | (Invited) I1-14 Dr. Zheng Zhang / Osaka University, Japan "On-line Monitoring of the Health State of Power Assembly During Power Cycling by Using Acoustic Emission Technology" | |
| 16:45 ~ 17:10 | (Invited) I1-15 Dr. Minyoung Lim / LG Chem Ltd., Korea "Novel Low Temperature Curable Photoimageable Dielectric Materials for Advanced Packaging" | (Invited) I1-16 Dr. Kwang-Seong Choi / Electronics and Telecommunications Research Institute (ETRI), Korea "Non-Fungible SISTRAB (Simultaneous Transfer and Bonding) Technology for Commercialization of micro LED Displays" | O1-7 Dr. Jagan Singh Meena, Su Bin Choi, Prof. Jong-Woong Kim / Jeonbuk National University, Korea Prof. Seung-Boo Jung / Sungkyunkwan University, Korea "Highly Stable Textile-based Capacitor Strain Sensor for Human Motion Detection Application" | (Invited) I1-17 Dr. Youngseok Kim / Hyundai Motor Company, Korea "Design of Double Side Cooling Power Module Structure to Reduce Thermal Stress for Next Generation PE System" | |
| 17:10 ~ 17:35 | (Invited) I1-18 Yoshinori Matsuura / Mitsui Mining and Smelting Co., Ltd., Japan "Introduction of the Rigid Carrier Substrates with Releasing Function for 2.5D Organic Interposer Packaging Solutions" | (Invited) I1-19 Prof. Keon Jae Lee / Korea Advanced Institute of Science and Technology (KAIST), Korea (On-line Presentation) "Flexible Piezoelectric-sensor and MicroLED" | O1-8 Eun Sung Oh, Dong Jun Kim, Dahye Lee, Dr. Hyeonjung Park, Jin-Woo Lee, Prof. Bumjoon J. Kim, Prof. Taek-Soo Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea Dr. Tae-Ik Lee / Korea Institute of Industrial Technology (KITECH), Korea "Thermo-mechanical Behavior of Poly (3-hexylthiophene-2,5-diy) Thin Films for Flexible and Stretchable Electronics" | (Invited) I1-20 Kuah Teng Hock Eric / ASMP Singapore Pte. Ltd. (ASMP), Singapore "Characterization of High Power Electronics Produced by ASMP Pressure Sintering Solution for Automotive" | Room Setting |
| 17:35 ~ 18:00 | O1-9 Dr. Mohamed Lamine Faycal BELLAREDJ, Dr. Jeremy Streque, Dr. Goran Miskovic / Silicon Austria Labs (SAL), Austria "Novel Lift-off based Process of Thick Copper Films on Organic Substrate for 5 µm Ultra-Fine Pitch Interconnects in Advanced Packaging" | (Invited) I1-21 Dr. Hee Yeoun Kim / National NanoFab Center (NNFC), Korea "Future of Wafer-level Packaging for Sensors : From Micro to Quantum" | O1-10 Myoung Song, Dr. Boo Soo Ma, Seung Jin Oh, Prof. Taek-Soo Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea "Liquid Surface Platform for Quantitatively Evaluating Fracture Toughness of Ultra-Thin Gold Films" | O1-11 Dr. Yong-Rae Jang, Prof. Hak-Sung Kim / Hanyang University, Korea Tae-Hwa Kim / Hyundai Motor Company, Korea Prof. Bongtae Han / University of Maryland, USA "Life-prediction of Ag Sintered Die Attach Interconnects for SiC Power Module Semiconductor" | |
| 18:05 ~ 20:00 | Welcome Reception (2F) | | | | |

Nov. 10, 2022 (Thu.)

| | Monterosso (B1F) | Forum 1 (3F) | Forum 2 (3F) | Forum 3 (3F) | Vernaza (3F) |
|---------------|---|--|--|--|---|
| | Hybrid Bonding 1 | 2.5D and 3D Interconnect 2 | Flexible and Printed Electronics 2 | Test and Reliability | Sponsor Session |
| Session Chair | Dr. Ah-Young Park | Prof. Hak-sung Kim | Prof. Suck Won Hong | Dr. Jiyong Park | |
| 9:00 ~ 9:25 | (Invited) I2-1 Dr. Bo-mook Chung / YMT Co., Ltd., Korea "Formation of Nanoscale Copper Roughness and Its Applications for Microelectronic Package Substrate" | (Invited) I2-2 Dr. Seung-jae Yune / BSP Inc., Korea "A Novel Technology for Crackless Through-Glass Via" | (Invited) I2-3 Prof. Tae-il Kim / Sungkyunkwan University, Korea "Unconventional Band Pass Filters for Bioelectronics" | O2-1 Sang Il Kim, Dr. Dug Joong Kim, Prof. Hak-Sung Kim / Hanyang University, Korea Do-Hyung Kim, Dong-Min Jang, Dr. Jin Woo Jang, Seung Yeong Lee / Samsung Electronics Co., Ltd., Korea "Corrosion Lifetime Prediction of Printed Circuit Board under Marine Atmosphere Condition Using Numerical Simulation Method" | Diamond LG Chem Hanwha NexMD Corporation Platinum Daeduck Electronics Co., Ltd. HAESUNG DS Co., Ltd. DISCO Corporation |
| 9:25 ~ 9:50 | O2-2 Jia-Juen Ong, Dr. Dinh-Phuc Tran, Prof. Chih Chen / National Yang Ming Chiao Tung University, Taiwan Dr. Wei-Lan Chiu / Industrial Technology Research Institute (ITRI), Taiwan "Reliability and Voids Analysis on Low Temperature nt-Cu/SiO2 Hybrid Bonds for Memory Stacking Applications" | (Invited) I2-4 YilHak Lee / DuPont Electronics and Industrial, Korea "Advanced Packaging Materials Solution for 3D Heterogeneous Integration" | (Invited) I2-5 Prof. Wenlong Cheng / Monash University, Australia "Gold Electronic Skins and Tattoos for Connected Healthcare" | O2-3 Kyoungyeon Lee, JaeBeom Shim, ByongJin Kim, Dr. JinYoung Khim / Amkor Technology Inc., Korea "Thermal Performance and Package Size Analysis by Design and Simulation" | Gold YMT Co., Ltd. SK hynix Inc. LB Semicon Inc. LG Innotek Tokyo Electron Korea (TEL) Ltd. PSK Holdings Inc. |
| 9:50 ~ 10:15 | (Invited) I2-6 Yong Chang Bum (Andy) / Applied Materials, Singapore "CZW Stacked Die Bonding for Memory and Logic" | (Invited) I2-7 Lewis(In-Soo) Kang / Nepes Corp., Korea "Fanout Technology Based Antenna-in-package (FO-AIP) for 5G mmWave Application" | O2-4 Prof. Benjamin Tee / National University of Singapore, Singapore "Scaling Electronic Skins for Performance and Sustainability" | (Invited) I2-8 Dr. Ralf Langhans / sentronics metrology GmbH, Germany "Novel Wafer Metrology Center for Microelectronic Packaging Applications" | Silver MK Electron Co., Ltd. Genesem Inc. Woowon Technology Co., Ltd. Kostek Systems Inc. Advanced Semiconductor Packaging Show |
| 10:15 ~ 10:40 | (Invited) I2-9 Lam Tak Wing, Percy / ASMP Singapore Pte. Ltd. (ASMP), Hong Kong "Interconnect Solutions for Heterogeneous Intergradation" | (Invited) I2-10 Prof. Eun-Ho Lee / Sungkyunkwan University, Korea "Deep Learning Algorithm to Predict Anisotropic Thermal Conductivity of Three-dimensionally Connected Semiconductor Package Layers" | (Invited) I2-11 Masayoshi Otomo / NAMICS Corporation, Japan "Low Temperature Sintering Nano Silver Paste for Flexible Applications" | O2-5 Dr. In-Seob Bae, Hong Chan Kim, Sung-Il Kang, Se Chuel Park / Haesung DS, Korea "Board Level Reliability according to the Structure and Surface Finish of QFN Substrates" | Booth LG Chem Hanwha NexMD Corporation OMA GOM Nepes Corp. Next-generation Intelligence Semiconductor Foundation Woowon Technology Co., Ltd. LB Semicon Inc. BSP Inc. |
| 10:40 ~ 10:50 | Coffee Break | | | | |
| 10:50 ~ 11:10 | Opening Remark (Monterosso (B1F)) | | | | |
| Session Chair | Prof. Sungdong Kim | | | | |
| 11:10 ~ 11:40 | Plenary Talk 1 - MJ (Myung-June) Lee / Intel Corporation, USA (On-line Presentation) "Advanced Packaging Technologies and Roadmap" (Monterosso (B1F)) | | | | |
| 11:40 ~ 12:10 | Plenary Talk 2 - Dr. Amram Eitan / Taiwan Semiconductor Manufacturing Co., Ltd. (TSMC), Taiwan "Bonding Technologies - Enabling Advanced Packaging" (Monterosso (B1F)) | | | | |
| 12:10 ~ 13:10 | Lunch (2F) | | | | |
| Session Chair | Prof. Young-Bae Park | | | | |
| 13:10 ~ 14:00 | Poster Presentation (Lobby (B1F & 3F)) | | | | |
| Session Chair | Prof. Gu-Sung Kim | | | | |
| 14:00 ~ 14:30 | Keynote Talk 3 - Dr. Un-Byoung Kang / Samsung Electronics Co., Ltd., Korea "Advanced Packaging Solution for Heterogeneous Integration - Status and Challenges" (Monterosso (B1F)) | | | | |
| 14:30 ~ 15:00 | Keynote Talk 4 - Dr. Jiho Kang / SK Hynix Inc., Korea "An Overview of the Past, Present and Future of 3D Device Technology" (Monterosso (B1F)) | | | | |
| 15:00 ~ 15:20 | Coffee Break | | | | |

| | Monterosso (B1F) | Forum 1 (3F) | Forum 2 (3F) | Forum 3 (3F) | Vernaza (3F) |
|---------------|--|--|--|---|---|
| | Hybrid Bonding 2 | Emerging Technologies 2 | Flexible and Printed Electronics 3 | Special Session 2 | Sponsor Session |
| Session Chair | Prof. Byungjoon Kim | Prof. Jae Yong Song | Prof. Tae-il Kim | | |
| 15:20 ~ 15:45 | (Invited) I2-12 Prof. Kyung Min Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea "Comprehensive Study on the Next-generation Chip-package Interface: Materials, Design, and Reliability" | O2-6 Dr. Zhenfeng Li, Prof. Peng He, Dr. Shuyue Zhang / Harbin Institute of Technology, China "Recent Prospective and Challenges of 3D Heterogeneous Integration" | (Invited) I2-13 Prof. Suckwon Hong / Pusan National University, Korea "Tissue-interfaced Microelectronic Devices for Therapeutic Modulation" | 15:00 ~ 18:00, Next-generation Electronic Packaging Materials Electronics and Telecommunications Research Institute (ETRI) (Close Session) | Diamond LG Chem Hanwha NexMD Corporation Platinum Daeduck Electronics Co., Ltd. HAESUNG DS Co., Ltd. DISCO Corporation |
| 15:45 ~ 16:10 | (Invited) I2-14 Prof. Sungdong Kim / Seoul National University of Science and Technology (SEoulUTECH), Korea "Low Temperature Hybrid Bonding Technology for Heterogeneous Packaging" | (Invited) I2-15 Seog Soon Kim / Unijet Co., Ltd., Korea "Introduction of the Inkjet Printing Technology for Semiconductor Packaging" | (Invited) I2-16 Prof. Sung Hun Jin / Incheon National University, Korea "Physically Detachable and Operationally Stable Inorganic Perovskite Photodetector Arrays for Broadband Flexible Optical Systems" | | Gold YMT Co., Ltd. SK hynix Inc. LB Semicon Inc. LG Innotek Tokyo Electron Korea (TEL) Ltd. PSK Holdings Inc. |
| 16:10 ~ 16:35 | (Invited) I2-17 Prof. Tadamoto Suga / Meisei University, Japan (On-line Presentation) "The Surface Activated Bonding for 3D Heterogeneous Integration" | (Invited) I2-18 Dr. Won-Seok Chang / Korea Institute of Machinery and Materials (KIMM), Korea "Development of Nanoimprinting and Maskless Lithography System and Process with Improved Patterning Quality for Advanced Packaging" | (Invited) I2-19 Prof. Yei Hwan Jung / Hanyang University, Korea "Strain-affected Stretchable Wireless Electronics" | | Silver MK Electron Co., Ltd. Genesem Inc. Woowon Technology Co., Ltd. Kostek Systems Inc. Advanced Semiconductor Packaging Show |
| 16:35 ~ 17:00 | (Invited) I2-20 Dr. Thomas Glinsner / EV Group (EVG), Austria "W2W Hybrid Bonding System for Next Generation Integration Scheme" | O2-7 Jun-Sang Park, Gun-Hee Kim / Protec Co., Ltd., Korea "Advanced Packaging Solutions with Dispensing System and Laser Assisted Bonding System" | (Invited) I2-21 Prof. Ki Jun Yu / Yonsei University, Korea "Unconventional Bio-integrated Electronics towards Human Machine Interface (HMI) Applications" | | Booth LG Chem Hanwha NexMD Corporation OMA GOM Nepes Corp. Next-generation Intelligence Semiconductor Foundation Woowon Technology Co., Ltd. LB Semicon Inc. BSP Inc. |
| 17:05 ~ 17:35 | General Meeting (Forum 1 (3F)) | | | | |
| 18:00 ~ 20:00 | Banquet and Headong Award Ceremony, Lucky Draw (Monterosso (B1F)) | | | | |

Nov. 11, 2022 (Fri.)

| | Monterosso (B1F) | Forum 1 (3F) | Forum 2 (3F) | Forum 3 (3F) | Vernaza (3F) |
|---------------|--|--|---|---|--|
| | Emerging Interconnect | Simulation and Modeling | Interconnect Reliability | Solder and PCB | Special Session 3 |
| Session Chair | Prof. Hyunsik Yoon | Prof. Taek-Soo Kim | Prof. Yoonchul Sohn | Dr. Yong-Ho Ko | |
| 9:00 ~ 9:25 | O3-1 Dr. Goran Miskovic, Dr. Mohamed Lamine Faycal Bellaredj / Silicon Austria Labs (SAL), Austria "Influence of Silicon Substrate Rear Surface Modification on Silver-based Backside Metallization Stack for Die-attach Packaging Applications" | O3-2 Jeong-Hyeon Baek, Dong-Woon Park, Prof. Hak-Sung Kim / Hanyang University, Korea Han-Sung Ryu, Gyung-Hwan Oh / Samsung Electronics Co., Ltd., Korea "Warpage Simulation of Bi-material Strip by the Effective Cure Shrinkage Measurement of EMC Using Dielectric and FBG Sensors" | O3-3 Xinyi Jing, Prof. Peng He, Prof. Shuyue Zhang / Harbin Institute of Technology, China "EBSD Analysis of BGA SAC305 300um Solder Ball at 1000 Cycles Thermal Shocks for Fan-out Wafer Level Packaging" | O3-4 You-Gwon Kim, Heon-Su Kim, Prof. Hak-Sung Kim / Hanyang University, Korea Do-Hyung Kim, Dong-Min Jang, Dr. Jin Woo Jang, Seung Yeong Lee / Samsung Electronics Co., Ltd., Korea "Prediction of Crack Type and Fatigue Life of Printed Circuit Board with Respect to Solder Composition under Repeated Thermal Cycle" | |
| 9:25 ~ 9:50 | O3-5 Woobin Kwon, Gahui Kim, Prof. Young-Bae Park / Andong National University, Korea Youn-Hye Kim, Yohai Kotsugi, Prof. Soo-Hyun Kim / Yeungnam University, Korea Yohei Kotsugi / TANAKA precious metals, Japan Dr. Kirak Son / Electronics and Telecommunications Research Institute (ETRI), Korea "ALD TIN Diffusion Barrier Thickness Effects on the Interfacial Adhesion Energy for Ru Interconnects" | O3-6 Jun Hwan Kim, Prof. Gil Ho Yoon / Hanyang University, Korea "Multi-component Topology Optimization Considering Mesh-independent Connection" | O3-7 Junmo Kim, Chang-Yeon Gu, Myoung Song, Prof. Taek-Soo Kim / Korea Advanced Institute of Science and Technology (KAIST), Korea Dr. Sung Woo Ma, Jin Hee Lee, Dr. Woong-Sun Lee / SK Hynix Inc., Korea "Effect of Span-to-Depth Ratio on Bending Behavior of Thin Molded Underfill" | O3-8 Dong-Woon Park, Myeong-Hyeon Yu, Prof. Hak-Sung Kim / Hanyang University, Korea "Improvement of Assembly Reliability by Optimization of Pad Design on Printed Circuit Board" | Room Setting |
| 9:50 ~ 10:15 | O3-9 Hyeok-Jin Chu, Sungdong Kim / Seoul National University of Science and Technology (SEoulUTECH), Korea "Implementation of 4-Layer RDLs for FOWLP with Planarization of Polymeric ILD" | O3-10 Heon-Su Kim, You-Gwon Kim, Prof. Hak-Sung Kim / Hanyang University, Korea Do-Hyung Kim, Dong-Min Jang, Dr. Jin Woo Jang, Seung Yeong Lee / Samsung Electronics Co., Ltd., Korea "Prediction of Solder Fatigue Life of Package by Automated Parametric Modeling Simulation Technique" | O3-11 Hui-Jin Um, Se-Min Lee, Hak-Sung Kim / Hanyang University, Korea Dae-Woong Lee, Sang-Yul Ha / SK Hynix Inc., Korea "Study on the Mixed-mode Delamination of Epoxy Mold Compound (EMC)/Printed Circuit Board(PCB) Interface Considering Various Temperature and Moisture Absorption" | O3-12 So-Yeon Jun, Tae-Young Lee, Sol-A Park, Dong-Gyu Choi, Jin-Kwan Kim, Sehoon Yoo / Korea Institute of Industrial Technology, Korea "Rheology and wettability of solder paste with average solder powder size" | |
| 10:15 ~ 10:30 | Coffee Break | | | | |
| | Monterosso (B1F) | | Forum 3 (3F) | Forum 3 (3F) | Forum 1 (3F) |
| | Young Engineers Forum | | Special Session 3 | Special Session 4 | Special Session 5 |
| 10:30 ~ 12:30 | Young Engineers Forum - Prof. Bongtae Han / University of Maryland, USA (Korean Language Session) "Part I: History of Packaging Technologies and Perspective" "Part II: Engineering Chronic Problem - Why difficult to find its root causes?" (현재치어링 고질적 문제 : 왜 근본 원인을 찾기 어려울까?) | | 10:30 ~ 12:30, Novel PCB Surface Finish for 5G/6G Package Application MK Chem&Tech Korea Institute of Industrial Technology(KITECH) Tech University of Korea (Close Session) | 10:30 ~ 12:30, Strategy for Next Generation Semiconductor Package Technology KMEPS (Close Session) | 10:30 ~ 13:30, AI Chiplet on Heterogeneous Integration Project: Design, Analysis, Interposer and Manufacturing ETRI, SEMCO, AMKOR, KAIST, SEoulUTECH, SNU, POSTECH, HANA Micron (Close Session) |
| 12:30 ~ 12:45 | ISMP Award Ceremony, Lucky Draw and Closing Remark (Monterosso (B1F)) | | | | |